

ELECTROOSMOTIC PUMPS USING POROUS FRITS  
FOR COOLING INTEGRATED CIRCUIT STACKS

Abstract of the Disclosure

5 A stack of heat generating integrated circuit chips may be provided with intervening cooling integrated circuit chips. The cooling integrated circuit chips may include microchannels for the flow of the cooling fluid. The cooling fluid may be pumped using the integrated electroosmotic pumps. Removal of cooling fluid gases may be accomplished using integrated re-combiners in some embodiments.